

NOTE:

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted⁽¹⁾

		ADS5424	UNIT
Supply voltage	AV _{DD} to GND	6	V
	DRV _{DD} to GND	5	
Analog input to GND		–0.3 to AV _{DD} + 0.3	V
Clock input to GND		–0.3 to AV _{DD} + 0.3	V
CLK to $\overline{\text{CLK}}$		±2.5	V
Digital data output to GND		–0.3 to DRV _{DD} + 0.3	V
Operating temperature range		–40 to 85	°C
Maximum junction temperature		150	°C
Storage temperature range		–65 to 150	°C

⁽¹⁾ Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

THERMAL CHARACTERISTICS⁽¹⁾

PARAMETER	TEST CONDITIONS	TYP	UNIT
θ_{JA}	Soldered slug, no airflow	22.5	°C/W
θ_{JA}	Soldered slug, 200-LPFM airflow	15.8	°C/W
θ_{JA}	Unsoldered slug, no airflow	33.3	°C/W
θ_{JA}	Unsoldered slug, 200-LPFM airflow	25.9	°C/W
θ_{JC}	Bottom of package (heatslug)	2	°C/W

⁽¹⁾ Using 25 thermal vias (5 x 5 array). See the Application Section.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because small parametric changes could cause the device not to meet its published specifications.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	MIN	TYP	MAX	UNIT
Supplies				
Analog supply voltage, AV _{DD}	4.75	5	5.25	V
Output driver supply voltage, DRV _{DD}	3	3.3	3.6	V
Analog Input				
Differential input range		2.2		V _{PP}
Input common-mode voltage, V _{CM}		2.4		V
Digital Output				
Maximum output load		10		pF
Clock Input				
ADCLK input sample rate (sine wave) 1/t _C	30		105	MSPS
Clock amplitude, sine wave, differential ⁽¹⁾		3		V _{PP}
Clock duty cycle ⁽²⁾		50%		
Open free-air temperature range	–40		85	°C

⁽¹⁾ See Figure 22 and Figure 23 for more information.

⁽²⁾ See Figure 21 for more information.

ELECTRICAL CHARACTERISTICS

Over full temperature range ($T_{MIN} = -40^{\circ}\text{C}$ to $T_{MAX} = 85^{\circ}\text{C}$), sampling rate = 105 MSPS, 50% clock duty cycle, $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, -1 dBFS differential input, and 3 V_{PP} differential sinusoidal clock, unless otherwise noted

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Resolution			14		Bits
Analog Inputs					
Differential input range			2.2		V_{PP}
Differential input resistance	See Figure 32		1		$k\Omega$
Differential input capacitance	See Figure 32		1.5		pF
Analog input bandwidth			570		MHz
Internal Reference Voltages					
Reference voltage, V_{REF}			2.4		V
Dynamic Accuracy					
No missing codes			Tested		
Differential linearity error, DNL	$f_{IN} = 5\text{ MHz}$	-0.95	± 0.5	1.5	LSB
Integral linearity error, INL	$f_{IN} = 5\text{ MHz}$		± 1.5		LSB
Offset error		-5	0	5	mV
Offset temperature coefficient			1.7		ppm/ $^{\circ}\text{C}$
Gain error		-5	0.9	5	%FS
PSRR			1		mV/V
Gain temperature coefficient			77		ppm/ $^{\circ}\text{C}$
Power Supply					
Analog supply current, I_{AVDD}	$V_{IN} = \text{full scale}, f_{IN} = 70\text{ MHz}$	$F_S = 92.16\text{ MSPS}$	355		mA
		$F_S = 105\text{ MSPS}$	355	410	
Output buffer supply current, I_{DRVDD}	$V_{IN} = \text{full scale}, f_{IN} = 70\text{ MHz}$	$F_S = 92.16\text{ MSPS}$	38		mA
		$F_S = 105\text{ MSPS}$	40	47	
Power dissipation	Total power with 10-pF load on each digital output to ground, $f_{IN} = 70\text{ MHz}$	$F_S = 92.16\text{ MSPS}$	1.9		W
		$F_S = 105\text{ MSPS}$	1.9	2.2	
Power-up time		$F_S = 105\text{ MSPS}$	20	100	ms

ELECTRICAL CHARACTERISTICS

Over full temperature range ($T_{MIN} = -40^{\circ}\text{C}$ to $T_{MAX} = 85^{\circ}\text{C}$), sampling rate = 105 MSPS, 50% clock duty cycle, $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, -1 dBFS differential input, and 3 V_{PP} differential sinusoidal clock, unless otherwise noted

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
Dynamic AC Characteristics						
Signal-to-noise ratio, SNR	f _{IN} = 10 MHz	F _S = 92.16 MSPS		74.5		dBc
		F _S = 105 MSPS		74.4		
	f _{IN} = 30 MHz	F _S = 92.16 MSPS		74.4		dBc
		F _S = 105 MSPS	73	74.3		dBc
	f _{IN} = 50 MHz	F _S = 92.16 MSPS		74.2		dBc
		F _S = 105 MSPS		74.2		
	f _{IN} = 70 MHz	F _S = 92.16 MSPS		74		dBc
		F _S = 105 MSPS	72.5	74		
	f _{IN} = 100 MHz	F _S = 92.16 MSPS		73.5		dBc
		F _S = 105 MSPS		73.5		
	f _{IN} = 170 MHz	F _S = 92.16 MSPS		72		dBc
		F _S = 105 MSPS		72		
	f _{IN} = 230 MHz	F _S = 92.16 MSPS		71.5		dBc
		F _S = 105 MSPS		71.5		
Spurious-free dynamic range, SFDR	f _{IN} = 10 MHz	F _S = 92.16 MSPS		94		dBc
		F _S = 105 MSPS		93		
	f _{IN} = 30 MHz	F _S = 92.16 MSPS		95		dBc
		F _S = 105 MSPS	85	95		dBc
	f _{IN} = 50 MHz	F _S = 92.16 MSPS		94		dBc
		F _S = 105 MSPS		93		
	f _{IN} = 70 MHz	F _S = 92.16 MSPS		89		dBc
		F _S = 105 MSPS		88		
	f _{IN} = 100 MHz	F _S = 92.16 MSPS		88		dBc
		F _S = 105 MSPS		87		
	f _{IN} = 170 MHz	F _S = 92.16 MSPS		73		dBc
		F _S = 105 MSPS		73		
	f _{IN} = 230 MHz	F _S = 92.16 MSPS		64		dBc
		F _S = 105 MSPS		64		
Signal-to-noise + distortion, SINAD	f _{IN} = 10 MHz	F _S = 92.16 MSPS		74.4		dBc
		F _S = 105 MSPS		74.3		
	f _{IN} = 30 MHz	F _S = 92.16 MSPS		74.3		dBc
		F _S = 105 MSPS	72.8	74.3		
	f _{IN} = 50 MHz	F _S = 92.16 MSPS		74.1		dBc
		F _S = 105 MSPS		74		
	f _{IN} = 70 MHz	F _S = 92.16 MSPS		74		dBc
		F _S = 105 MSPS		73.9		
	f _{IN} = 100 MHz	F _S = 92.16 MSPS		73.3		dBc
		F _S = 105 MSPS		73.3		
	f _{IN} = 170 MHz	F _S = 92.16 MSPS		69.3		dBc
		F _S = 105 MSPS		69.1		
	f _{IN} = 230 MHz	F _S = 92.16 MSPS		63.4		dBc
		F _S = 105 MSPS		63.4		

ELECTRICAL CHARACTERISTICS

Over full temperature range ($T_{MIN} = -40^{\circ}\text{C}$ to $T_{MAX} = 85^{\circ}\text{C}$), sampling rate = 105 MSPS, 50% clock duty cycle, $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, -1 dBFS differential input, and 3 V_{PP} differential sinusoidal clock, unless otherwise noted

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Second harmonic, HD2	$f_{IN} = 10\text{ MHz}$		100		dBc
	$f_{IN} = 30\text{ MHz}$		105		dBc
	$f_{IN} = 50\text{ MHz}$		98		dBc
	$f_{IN} = 70\text{ MHz}$		98		dBc
	$f_{IN} = 100\text{ MHz}$		98		dBc
	$f_{IN} = 170\text{ MHz}$		98		dBc
	$f_{IN} = 230\text{ MHz}$		96		dBc
Third harmonic, HD3	$f_{IN} = 10\text{ MHz}$		93		dBc
	$f_{IN} = 30\text{ MHz}$		95		dBc
	$f_{IN} = 50\text{ MHz}$		93		dBc
	$f_{IN} = 100\text{ MHz}$		87		dBc
	$f_{IN} = 170\text{ MHz}$		73		dBc
	$f_{IN} = 230\text{ MHz}$		64		dBc
Worst-harmonic / spur (other than HD2 and HD3)	$f_{IN} = 10\text{ MHz}$		93		dBc
	$f_{IN} = 30\text{ MHz}$		95		dBc
	$f_{IN} = 50\text{ MHz}$		93		dBc
	$f_{IN} = 70\text{ MHz}$		88		dBc
	$f_{IN} = 100\text{ MHz}$		88		dBc
	$f_{IN} = 170\text{ MHz}$		88		dBc
	$f_{IN} = 230\text{ MHz}$		88		dBc
RMS idle channel noise	Input pins tied together		0.9		LSB

DIGITAL CHARACTERISTICS

Over full temperature range ($T_{MIN} = -40^{\circ}\text{C}$ to $T_{MAX} = 85^{\circ}\text{C}$), $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, unless otherwise noted

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Digital Outputs					
Low-level output voltage	$C_{LOAD} = 10\text{ pF}^{(1)}$		0.1	0.6	V
High-level output voltage	$C_{LOAD} = 10\text{ pF}^{(1)}$	2.6	3.2		V
Output capacitance			3		pF
DMID			$DRV_{DD}/2$		V

⁽¹⁾ Equivalent capacitance to ground of (load + parasitics of transmission lines).

TIMING CHARACTERISTICS⁽³⁾

Over full temperature range, $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, sampling rate = 105 MSPS

PARAMETER	DESCRIPTION	MIN	TYP	MAX	UNIT
Aperture Time					
t_A	Aperture delay		500		ps
t_J	Clock slope independent aperture uncertainty (jitter)		150		fs
k_J	Clock slope dependent jitter factor		50		μV
Clock Input					
t_{CLK}	Clock period		9.5		ns
$t_{CLKH}^{(1)}$	Clock pulsewidth high		4.75		ns
$t_{CLKL}^{(1)}$	Clock pulsewidth low		4.75		ns
Clock to DataReady (DRY)					
t_{DR}	Clock rising 50% to DRY falling 50%	2.8	3.9	4.7	ns
t_{C_DR}	Clock rising 50% to DRY rising 50%		$t_{DR} + t_{CLKH}$		ns
$t_{C_DR_50\%}$	Clock rising 50% to DRY rising 50% with 50% duty cycle clock	7.6	8.7	9.5	ns
Clock to DATA, OVR⁽⁴⁾					
t_r	Data V_{OL} to data V_{OH} (rise time)		2		ns
t_f	Data V_{OH} to data V_{OL} (fall time)		2		ns
L	Latency		3		Cycles
$t_{su(C)}$	Valid DATA ⁽²⁾ to clock 50% with 50% duty cycle clock (setup time)	1.8	3.4		ns
$t_{h(C)}$	Clock 50% to invalid DATA ⁽²⁾ (hold time)	2.6	3.6		ns
DataReady (DRY) to DATA, OVR⁽⁴⁾					
$t_{su(DR_50\%)}$	Valid DATA ⁽²⁾ to DRY 50% with 50% duty cycle clock (setup time)	1.8	2.6		ns
$t_{h(DR_50\%)}$	DRY 50% to invalid DATA ⁽²⁾ with 50% duty cycle clock (hold time)	3.9	4.4		ns

(1) See Figure 21 for more information.

(2) See V_{OH} and V_{OL} levels.

(3) All values obtained from design and characterization.

(4) Data is updated with clock rising edge or DRY falling edge.

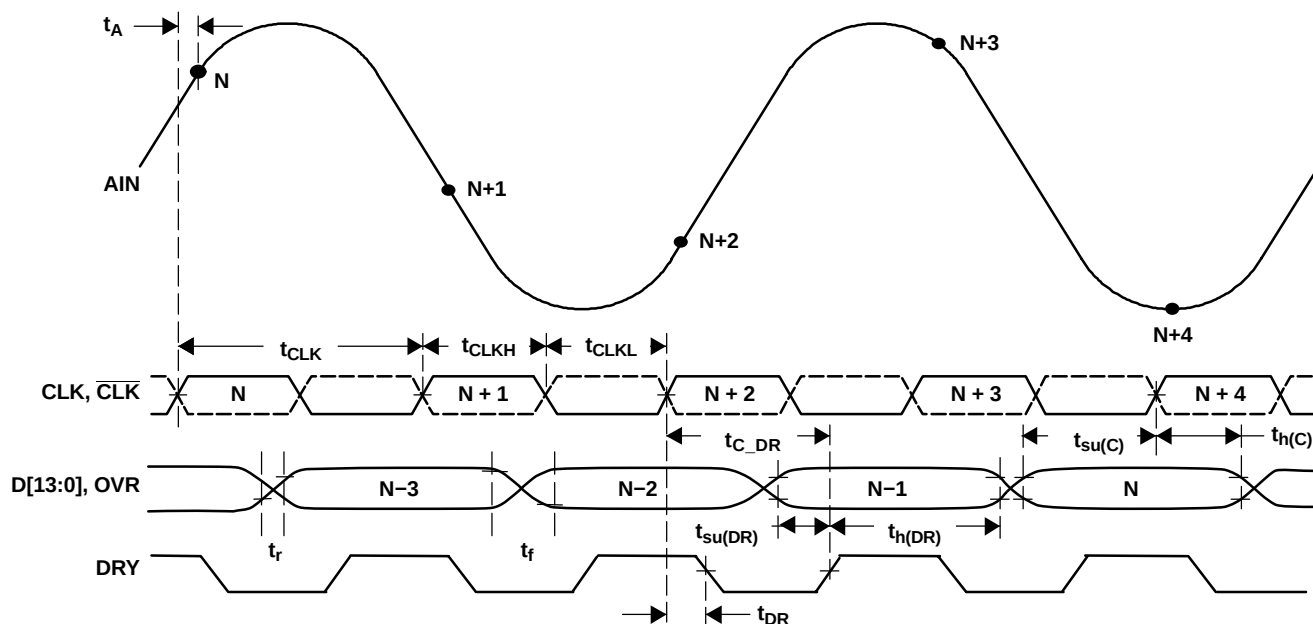
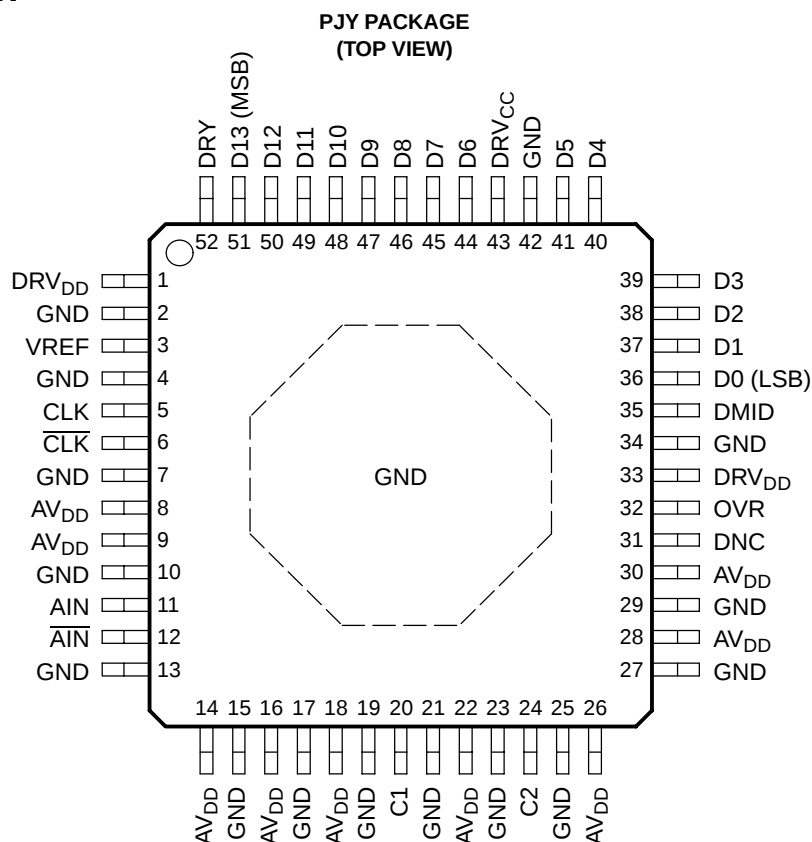


Figure 1. Timing Diagram

PIN CONFIGURATION



PIN ASSIGNMENTS

TERMINAL		DESCRIPTION
NAME	NO.	
DRV _{DD}	1, 33, 43	3.3 V power supply, digital output stage only
GND	2, 4, 7, 10, 13, 15, 17, 19, 21, 23, 25, 27, 29, 34, 42	Ground
VREF	3	2.4 V reference. Bypass to ground with a 0.1-μF microwave chip capacitor.
CLK	5	Clock input. Conversion initiated on rising edge.
$\overline{\text{CLK}}$	6	Complement of CLK, differential input
AV _{DD}	8, 9, 14, 16, 18, 22, 26, 28, 30	5 V analog power supply
AIN	11	Analog input
$\overline{\text{AIN}}$	12	Complement of AIN, differential analog input
C1	20	Internal voltage reference. Bypass to ground with a 0.1-μF chip capacitor.
C2	24	Internal voltage reference. Bypass to ground with a 0.1-μF chip capacitor.
DNC	31	Do not connect
OVR	32	Overrange bit. A logic level high indicates the analog input exceeds full scale.
DMID	35	Output data voltage midpoint. Approximately equal to (DV _{CC})/2
D0 (LSB)	36	Digital output bit (least significant bit); two's complement
D1–D5, D6–D12	37–41, 44–50	Digital output bits in two's complement
D13 (MSB)	51	Digital output bit (most significant bit); two's complement
DRY	52	Data ready output

DEFINITION OF SPECIFICATIONS

Analog Bandwidth

The analog input frequency at which the power of the fundamental is reduced by 3 dB with respect to the low frequency value.

Aperture Delay

The delay between the rising edge of the input sampling clock and the actual time at which the sampling occurs.

Aperture Uncertainty (Jitter)

The sample-to-sample variation in aperture delay.

Clock Pulse Width/Duty Cycle

The duty cycle of a clock signal is the ratio of the time the clock signal remains at a logic high (clock pulse width) to the period of the clock signal. Duty cycle is typically expressed as a percentage. A perfect differential sine wave clock results in a 50% duty cycle.

Maximum Conversion Rate

The maximum sampling rate at which certified operation is given. All parametric testing is performed at this sampling rate unless otherwise noted.

Minimum Conversion Rate

The minimum sampling rate at which the ADC functions.

Differential Nonlinearity (DNL)

An ideal ADC exhibits code transitions at analog input values spaced exactly 1 LSB apart. The DNL is the deviation of any single step from this ideal value, measured in units of LSB.

Integral Nonlinearity (INL)

The INL is the deviation of the ADC's transfer function from a best fit line determined by a least squares curve fit of that transfer function, measured in units of LSB.

Gain Error

The gain error is the deviation of the ADC's actual input full-scale range from its ideal value. The gain error is given as a percentage of the ideal input full-scale range.

Offset Error

The offset error is the difference, given in number of LSBs, between the ADC's actual value average idle channel output code and the ideal average idle channel output code. This quantity is often mapped into mV.

Temperature Drift

The temperature drift coefficient (with respect to gain error and offset error) specifies the change per degree celcius of the parameter from T_{MIN} or T_{MAX} . It is computed as the maximum variation of that parameter over the whole temperature range divided by $T_{MAX} - T_{MIN}$.

Signal-to-Noise Ratio (SNR)

SNR is the ratio of the power of the fundamental (P_S) to the noise floor power (P_N), excluding the power at dc and the first five harmonics.

$$SNR = 10\log_{10} \frac{P_S}{P_N}$$

SNR is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference or dBFS (dB to full scale) when the power of the fundamental is extrapolated to the converter's full-scale range.

Signal-to-Noise and Distortion (SINAD)

SINAD is the ratio of the power of the fundamental (P_S) to the power of all the other spectral components including noise (P_N) and distortion (P_D), but excluding dc.

$$SINAD = 10\log_{10} \frac{P_S}{P_N + P_D}$$

SINAD is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference or dBFS (dB to full scale) when the power of the fundamental is extrapolated to the converter's full-scale range.

Total Harmonic Distortion (THD)

THD is the ratio of the fundamental power (P_S) to the power of the first five harmonics (P_D).

$$\text{THD} = 10\text{Log}_{10} \frac{P_S}{P_D}$$

THD is typically given in units of dBc (dB to carrier).

Spurious-Free Dynamic Range (SFDR)

The ratio of the power of the fundamental to the highest other spectral component (either spur or harmonic). SFDR is typically given in units of dBc (dB to carrier).

Two-Tone Intermodulation Distortion

IMD3 is the ratio of the power of the fundamental (at frequencies f_1 , f_2) to the power of the worst spectral component at either frequency $2f_1 - f_2$ or $2f_2 - f_1$. IMD3 is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference or dBFS (dB to full scale) when it is referred to the full-scale range.

TYPICAL CHARACTERISTICS

Typical values are at $T_A = 25^\circ\text{C}$, $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, differential input amplitude = -1 dBFS , sampling rate = 105 MSPS , 3 V_{PP} sinusoidal clock, 50% duty cycle, 16k FFT points, unless otherwise noted

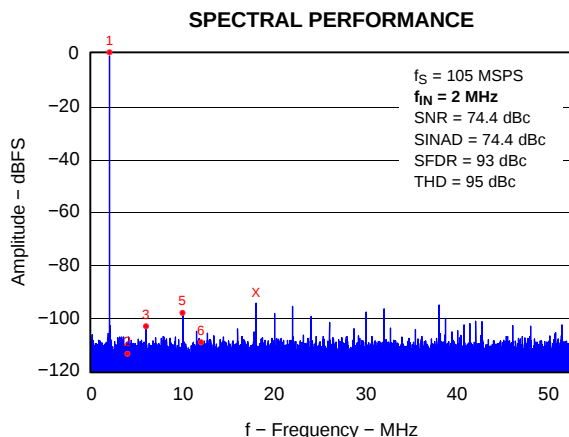


Figure 2

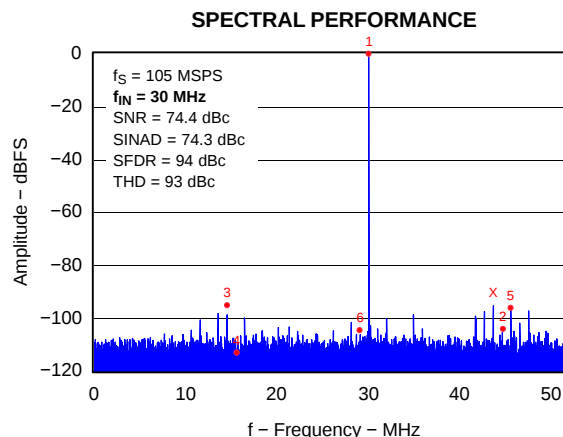


Figure 3

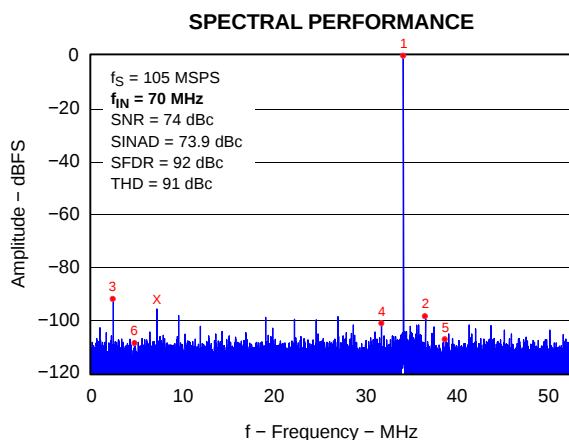


Figure 4

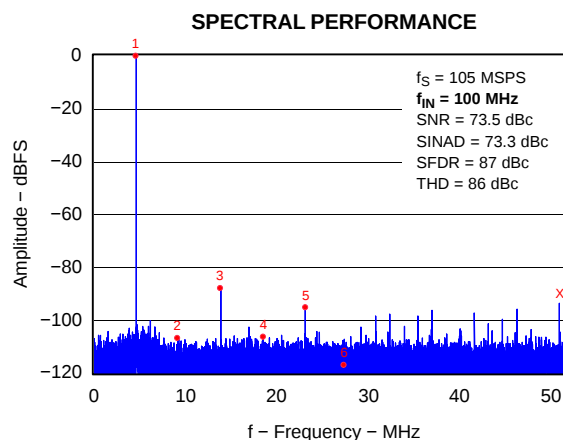


Figure 5

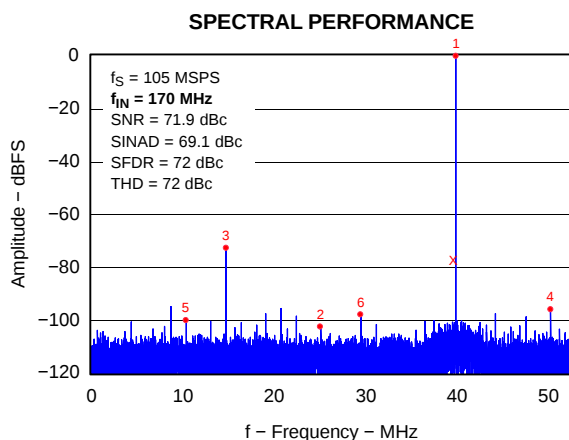


Figure 6

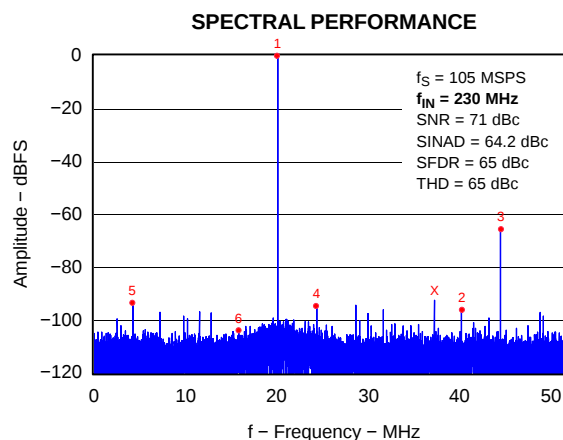


Figure 7

Typical values are at $T_A = 25^\circ\text{C}$, $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, differential input amplitude = -1 dBFS , sampling rate = 105 MSPS , 3 V_{pp} sinusoidal clock, 50% duty cycle, 16k FFT points, unless otherwise noted

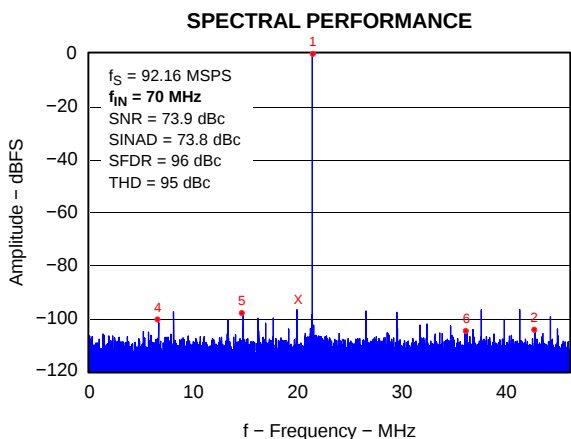


Figure 8

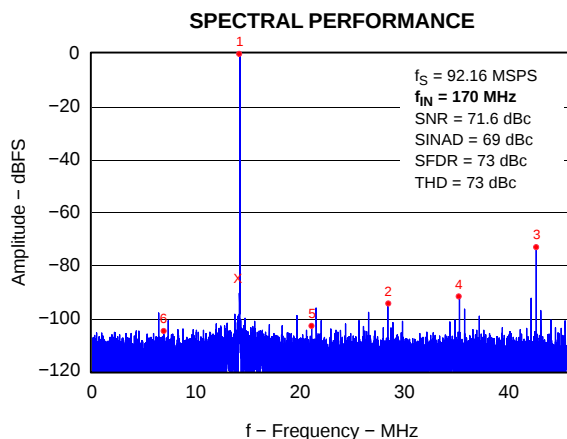


Figure 9

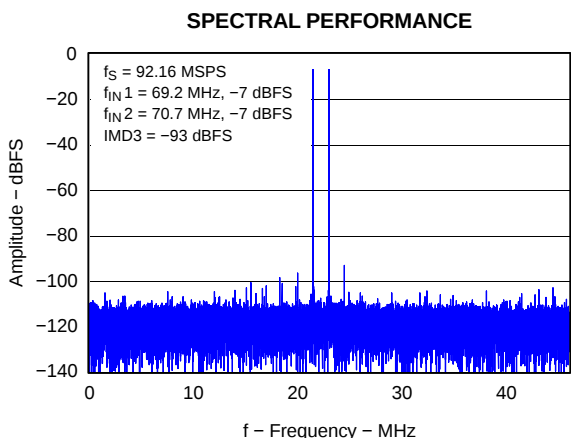


Figure 10

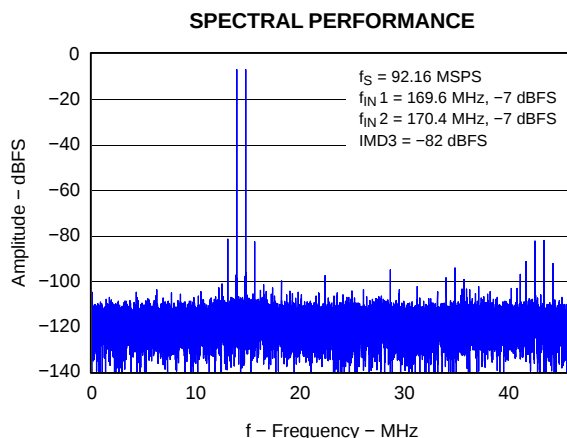


Figure 11

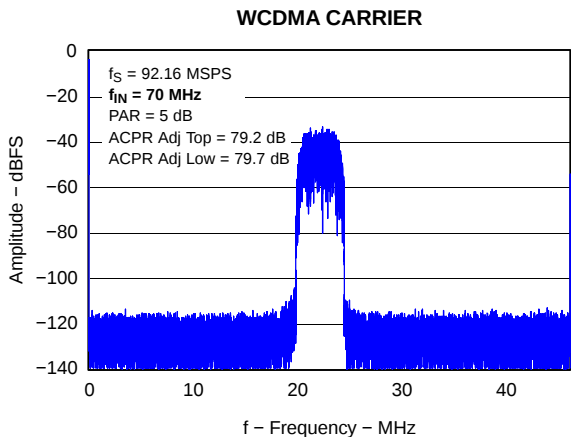


Figure 12

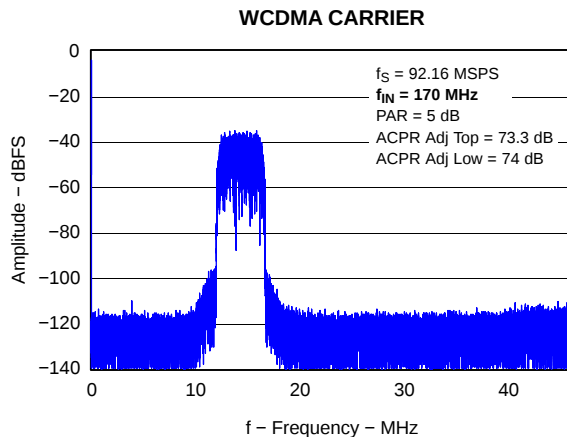
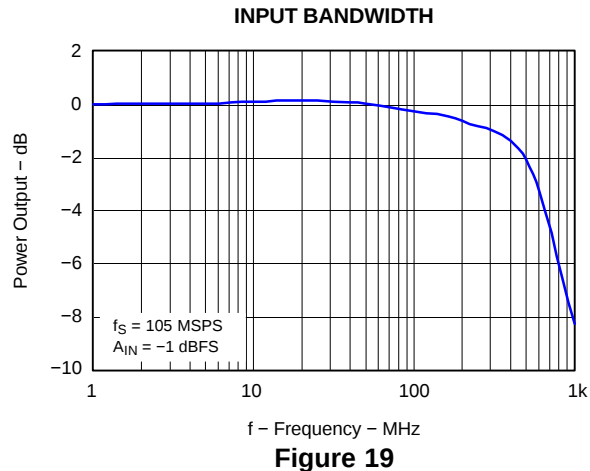
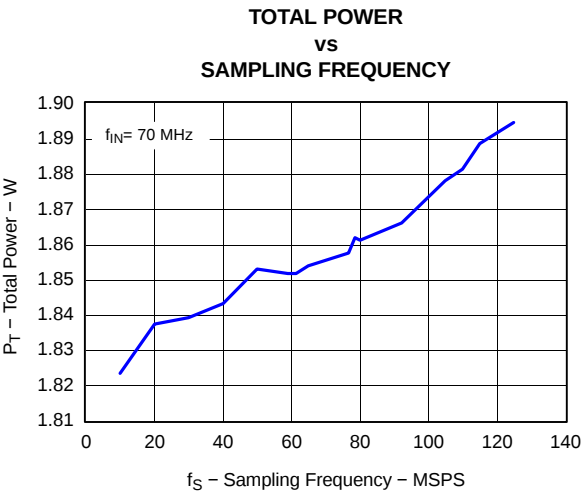
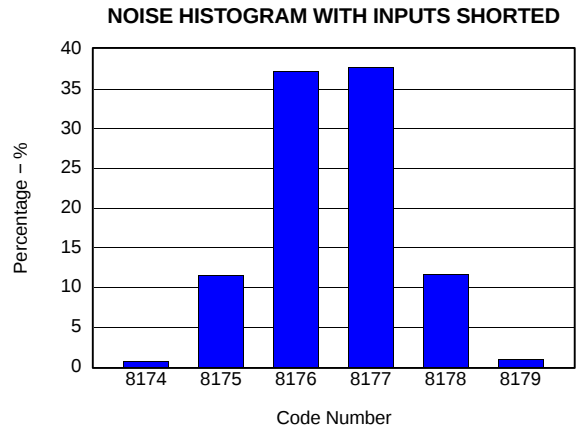
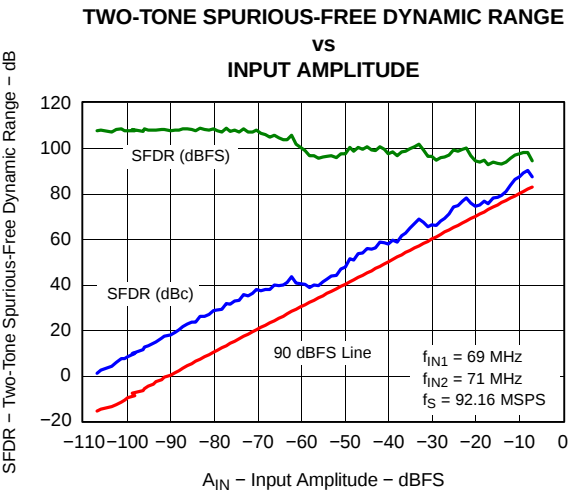
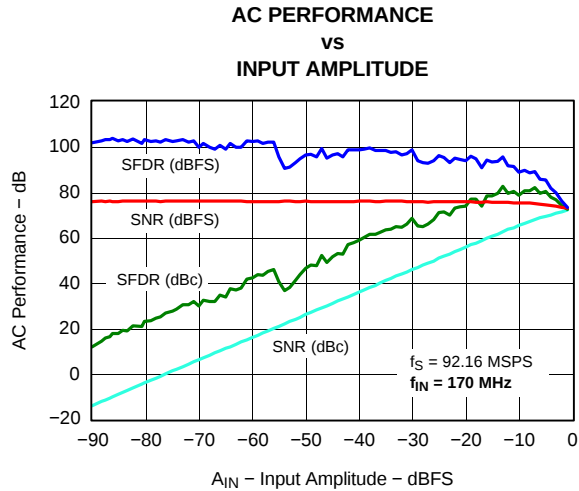
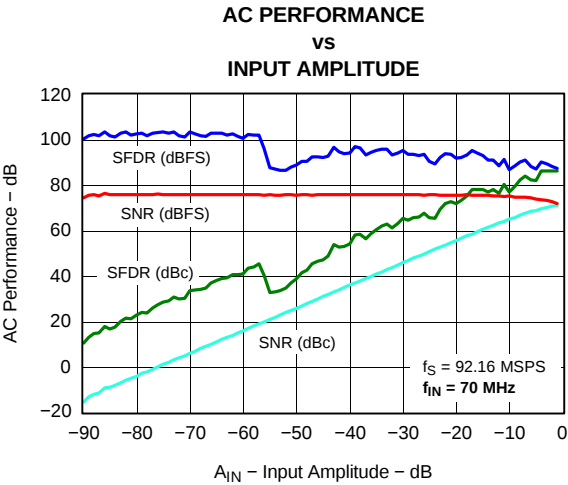


Figure 13

Typical values are at $T_A = 25^\circ\text{C}$, $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, differential input amplitude = -1 dBFS , sampling rate = 105 MSPS , 3 V_{PP} sinusoidal clock, 50% duty cycle, 16k FFT points, unless otherwise noted



Typical values are at $T_A = 25^\circ\text{C}$, $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, differential input amplitude = -1 dBFS , sampling rate = 105 MSPS, 3 V_{pp} sinusoidal clock, 50% duty cycle, 16k FFT points, unless otherwise noted

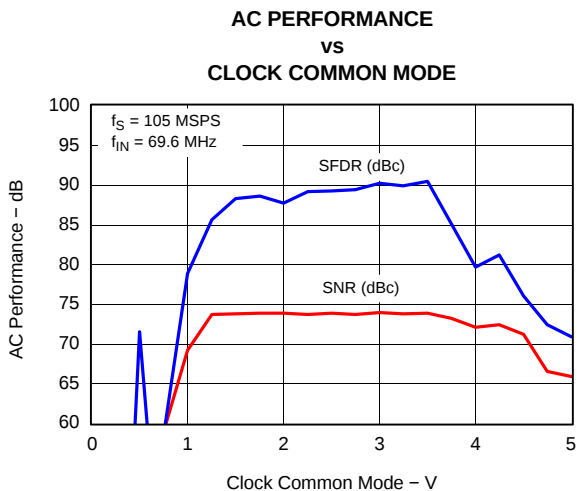


Figure 20

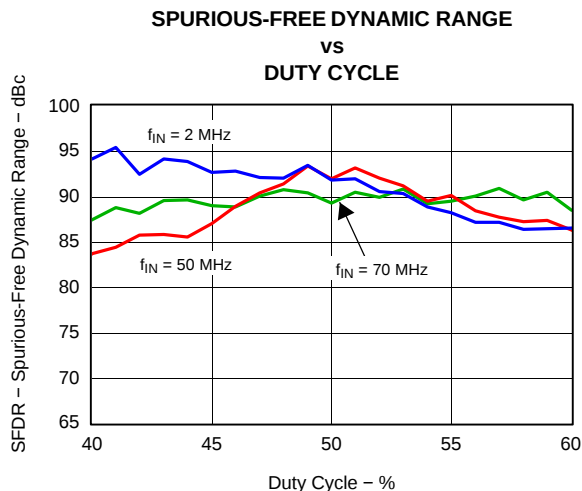


Figure 21

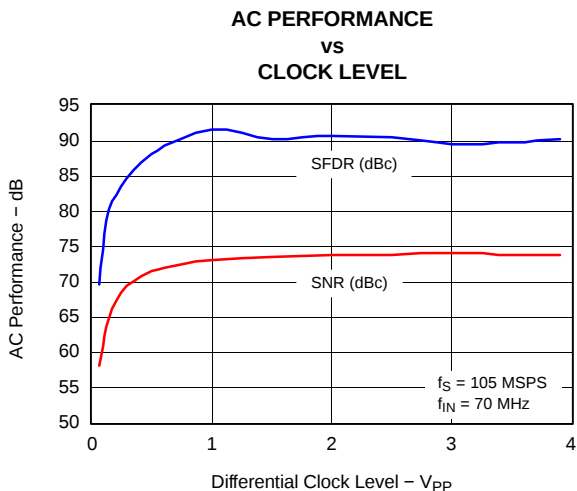


Figure 22

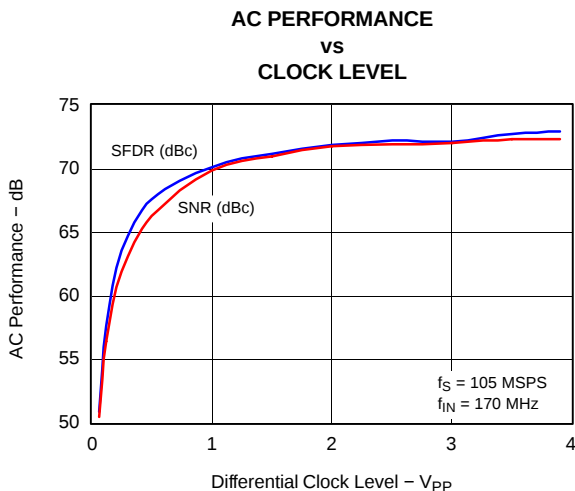


Figure 23

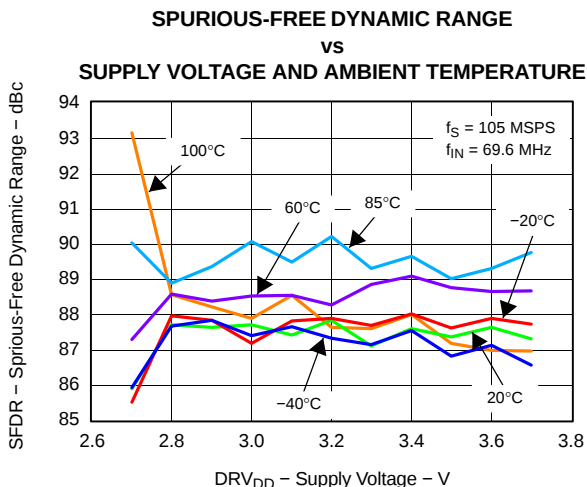


Figure 24

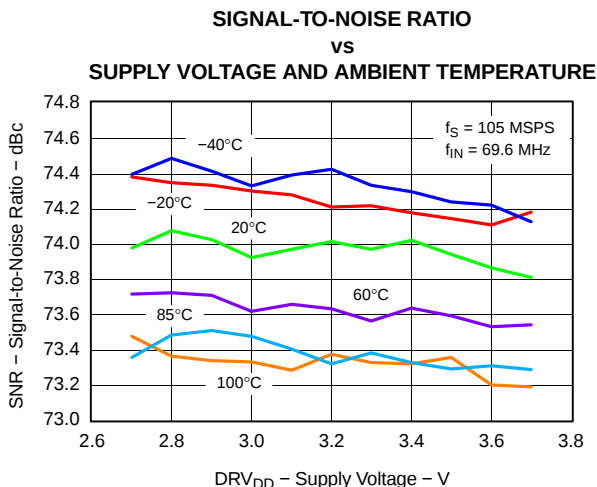


Figure 25

Typical values are at $T_A = 25^\circ\text{C}$, $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, differential input amplitude = -1 dBFS , sampling rate = 105 MSPS , 3 V_{PP} sinusoidal clock, 50% duty cycle, 16k FFT points, unless otherwise noted

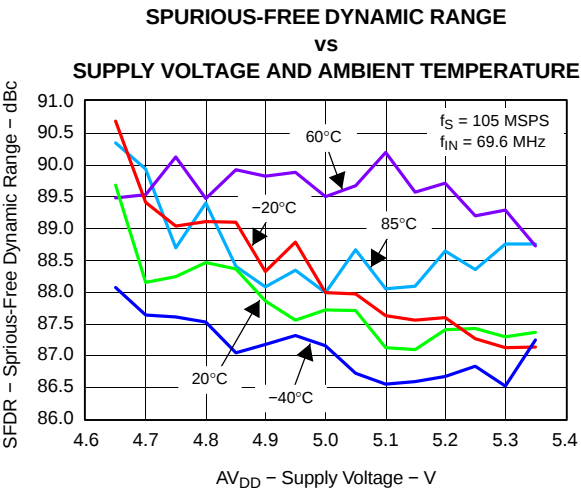


Figure 26

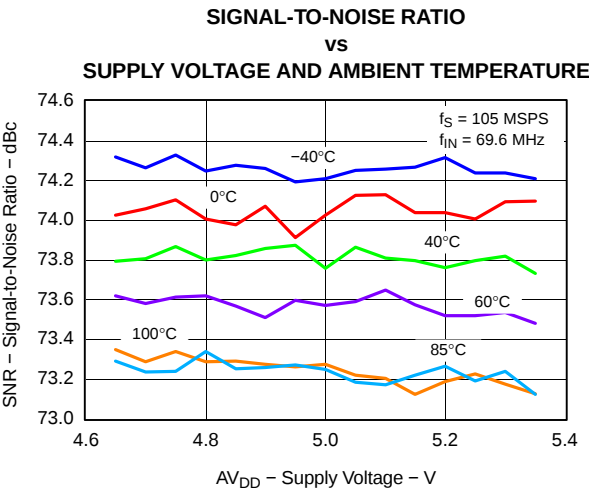


Figure 27

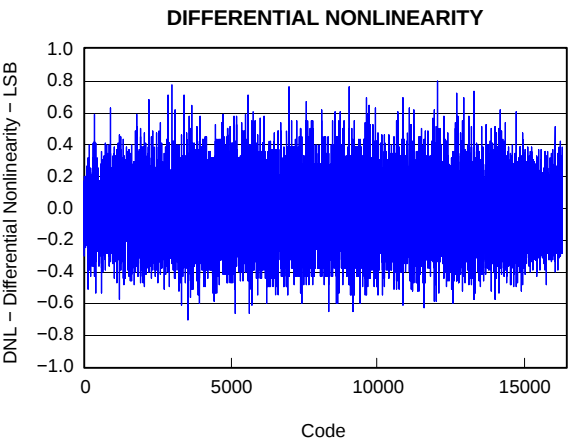


Figure 28

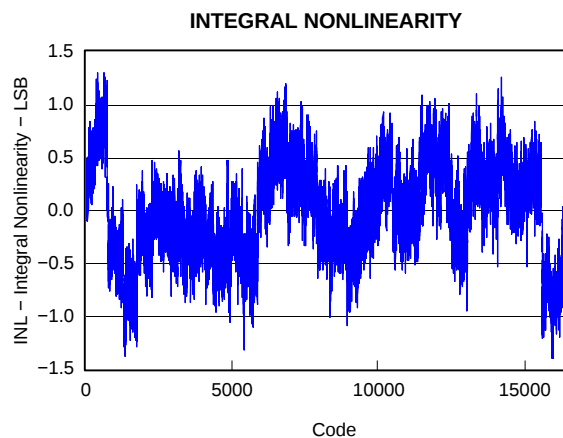


Figure 29

Typical values are at $T_A = 25^\circ\text{C}$, $AV_{DD} = 5\text{ V}$, $DRV_{DD} = 3.3\text{ V}$, differential input amplitude = -1 dBFS , sampling rate = 105 MSPS, 3 V_{pp} sinusoidal clock, 50% duty cycle, 16k FFT points, unless otherwise noted

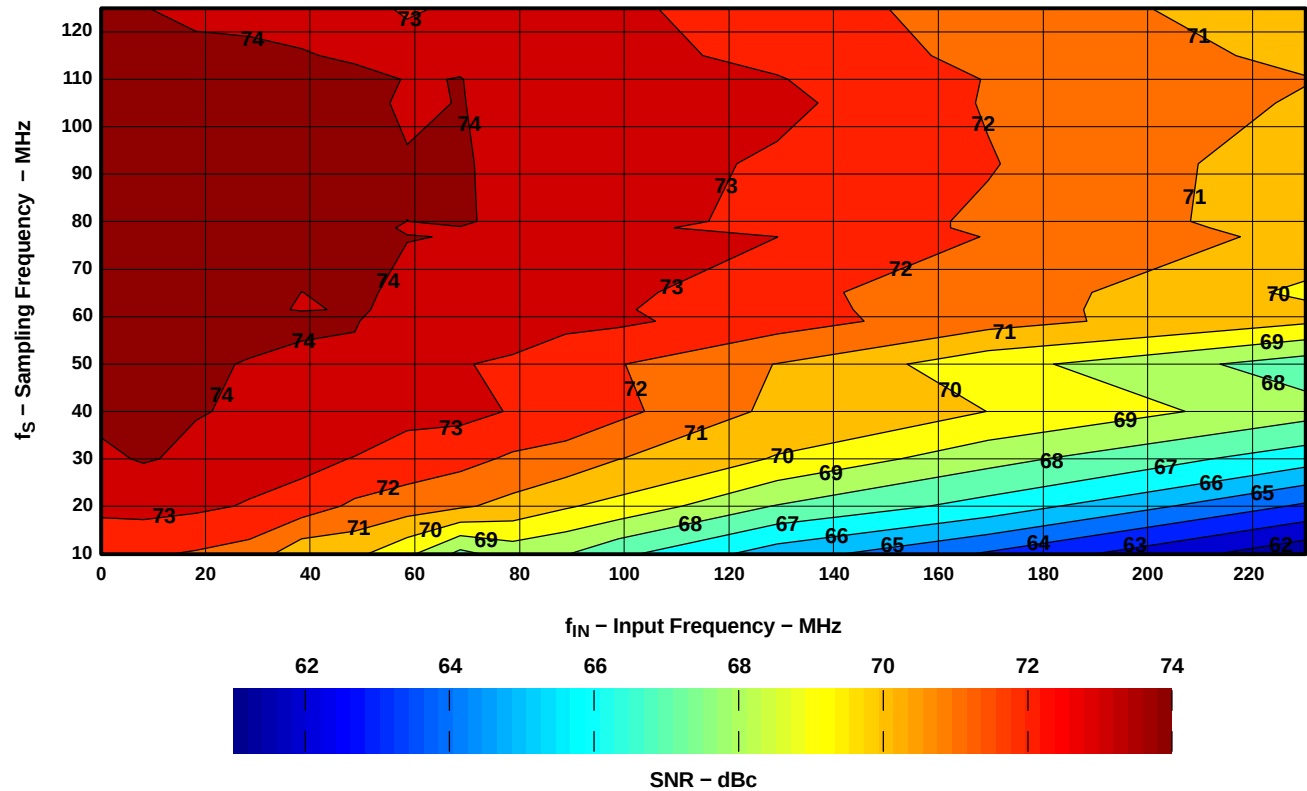


Figure 30.

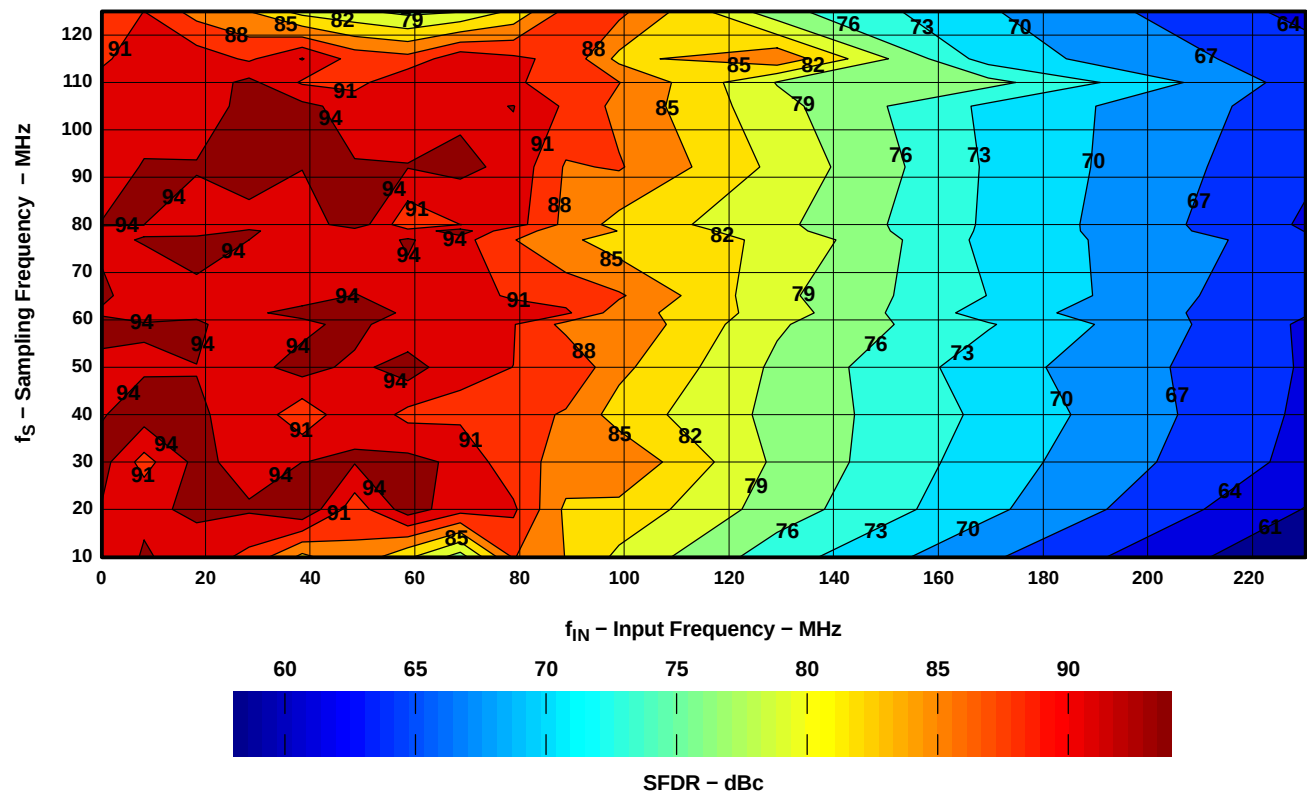


Figure 31.

EQUIVALENT CIRCUITS

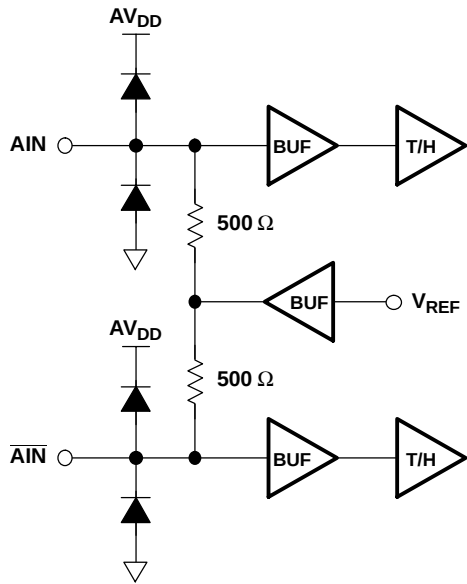


Figure 32. Analog Input

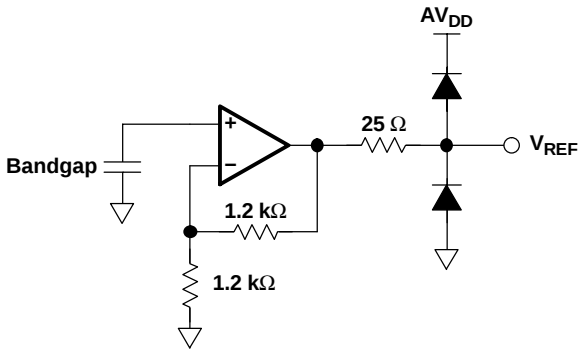


Figure 35. Reference

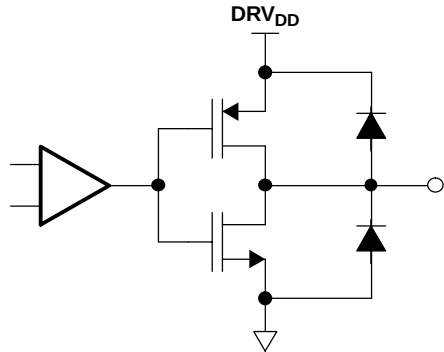


Figure 33. Digital Output

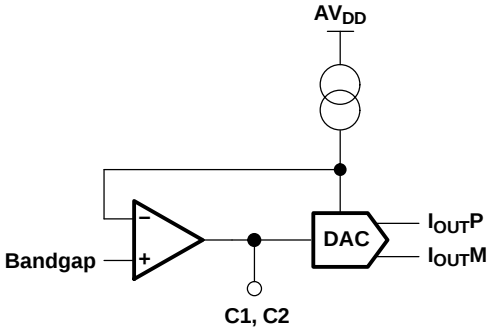


Figure 36. Decoupling Pin

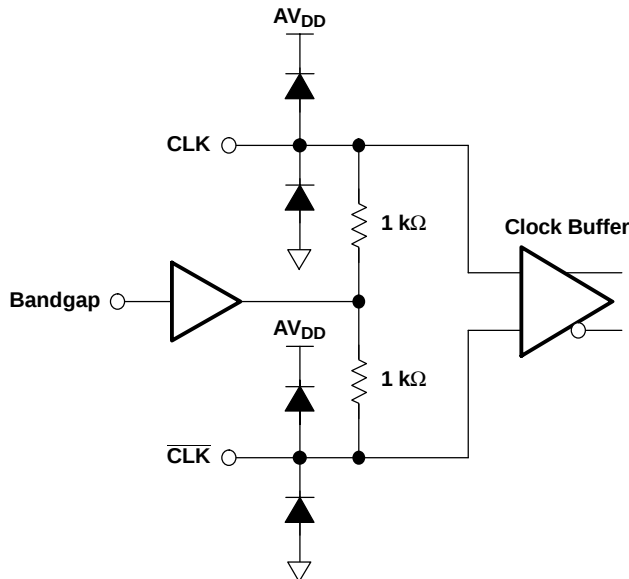


Figure 34. Clock Input

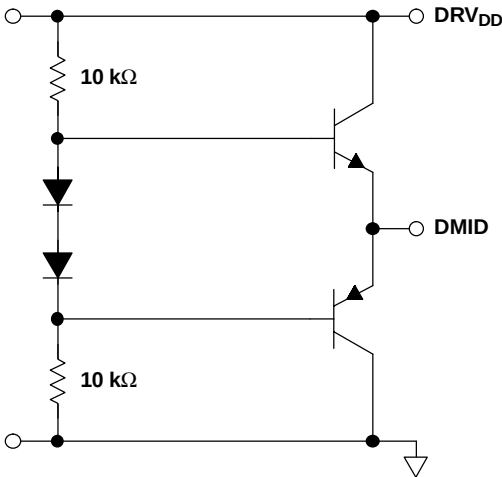


Figure 37. DMID Generation

APPLICATION INFORMATION

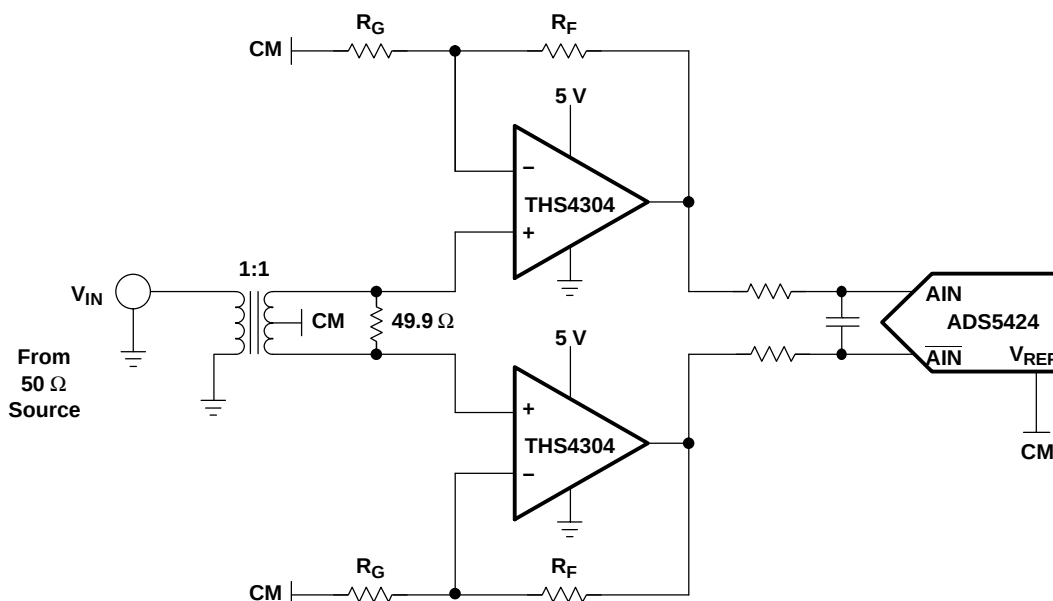


Figure 40. Using the THS4304 With the ADS5424

Besides these, Texas Instruments offers a wide selection of single-ended operational amplifiers (including the THS3201, THS3202 and OPA847) that can be selected depending on the application. An RF gain block amplifier, such as Texas Instrument's THS9001, can also be used with an RF transformer for high input frequency applications. For applications requiring dc-coupling with the signal source, instead of using a topology with three single ended amplifiers, a differential input/differential output amplifier like the THS4509 (see Figure 41) can be used, which minimizes board space and reduce number of components.

Figure 43 shows their combined SNR and SFDR performance versus frequency with -1 dBFS input signal level and sampling at 80MSPS.

On this configuration, the THS4509 amplifier circuit provides 10 dB of gain, converts the single-ended input to differential, and sets the proper input common-mode voltage to the ADS5424.

The 225 Ω resistors and 2.7 pF capacitor between the THS4509 outputs and ADS5424 inputs (along with the input capacitance of the ADC) limit the bandwidth of the signal to about 100 MHz (-3 dB).

For this test, an Agilent signal generator is used for the signal source. The generator is an ac-coupled 50 Ω source. A band-pass filter is inserted in series with the input to reduce harmonics and noise from the signal source.

Input termination is accomplished via the 69.8 Ω resistor and 0.22 μ F capacitor to ground in conjunction with the input impedance of the amplifier circuit. A 0.22 μ F capacitor and 49.9 Ω resistor is inserted to ground across the 69.8 Ω resistor and 0.22 μ F capacitor on the alternate input to balance the circuit.

Gain is a function of the source impedance, termination, and 348 Ω feedback resistor. See the THS4509 data sheet for further component values to set proper 50 Ω termination for other common gains.

Since the ADS5424 recommended input common-mode voltage is +2.4 V, the THS4509 is operated from a single power supply input with $V_{S+} = +5$ V and $V_{S-} = 0$ V (ground). This maintains maximum headroom on the internal transistors of the THS4509.

APPLICATION INFORMATION

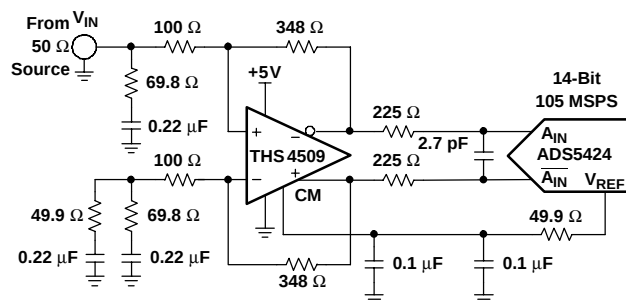


Figure 41. Using the THS4509 With the ADS5424

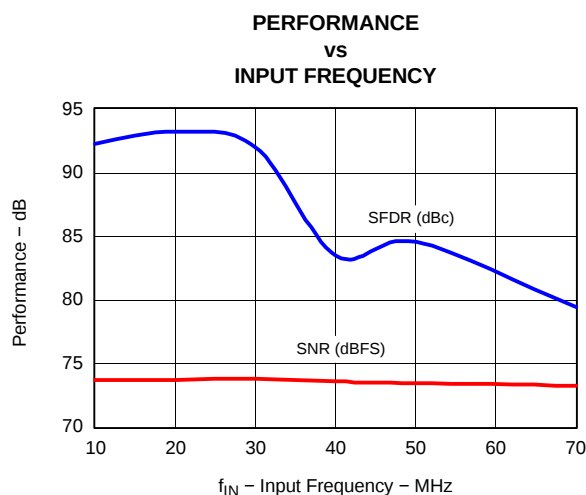


Figure 42. Performance vs Input Frequency for the THS4509 + ADS5424 Configuration

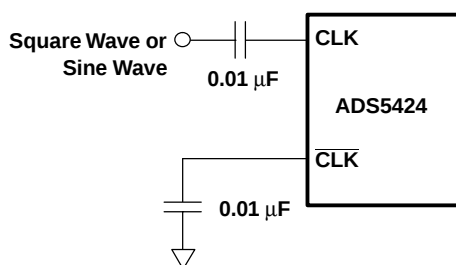


Figure 43. Single-Ended Clock

CLOCK INPUTS

The ADS5424 clock input can be driven with either a differential clock signal or a single-ended clock input, with little or no difference in performance between both

configurations. In low input frequency applications, where jitter may not be a big concern, the use of single-ended clock (see Figure 43) could save some cost and board space without any trade-off in performance. When driven on this configuration, it is best to connect CLKM (pin 11) to ground with a 0.01 μ F capacitor, while CLKP is ac-coupled with a 0.01 μ F capacitor to the clock source, as shown in Figure 40.

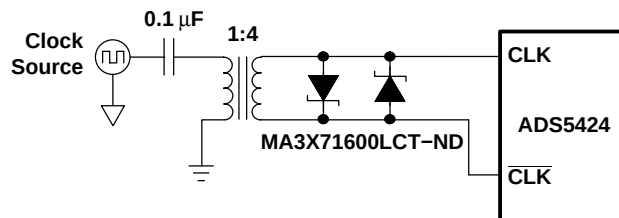


Figure 44. Differential Clock

Nevertheless, for jitter sensitive applications, the use of a differential clock will have some advantages (as with any other ADCs) at the system level. The first advantage is that it allows for common-mode noise rejection at the PCB level. A further analysis (see Clocking High Speed Data Converters, SLYT075) reveals one more advantage. The following formula describes the different contributions to clock jitter:

$$(\text{Jitter}_{\text{total}})^2 = (\text{EXT_jitter})^2 + (\text{ADC_jitter})^2 = (\text{EXT_jitter})^2 + (\text{ADC_int})^2 + (\text{K}/\text{clock_slope})^2$$

The first term would represent the external jitter, coming from the clock source, plus noise added by the system on the clock distribution, up to the ADC. The second term is the ADC contribution, which can be divided in two portions. The first does not depend directly on any external factor. That is the best we can get out of our ADC. The second contribution is a term inversely proportional to the clock slope. The faster the slope, the smaller this term will be. As an example, we could compute the ADC jitter contribution from a sinusoidal input clock of 3 V_{pp} amplitude and $F_s = 80$ MSPS:

$$\text{ADC_jitter} = \sqrt{((150\text{fs})^2 + (5 \times 10^{-5} / (1.5 \times 2 \times \pi \times 80 \times 10^6))^2)} = 164\text{fs}$$

The use of differential clock allows for the use of bigger clock amplitudes without exceeding the absolute maximum ratings. This, on the case of sinusoidal clock, results on higher slew rates which minimizes the impact of the jitter factor inversely proportional to the clock slope.

APPLICATION INFORMATION

Figure 44 shows this approach. The back-to-back Schottky can be added to limit the clock amplitude in cases where this would exceed the absolute maximum ratings, even when using a differential clock. Figure 22 and Figure 23 show the performance versus input clock amplitude for a sinusoidal clock.

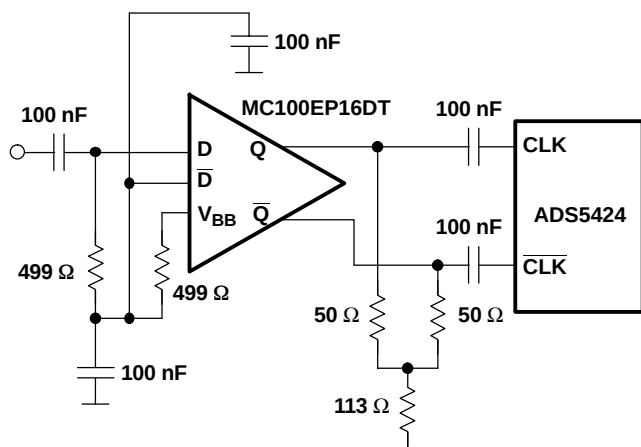


Figure 45. Differential Clock Using PECL Logic

Another possibility is the use of a logic based clock, as PECL. In this case, the slew rate of the edges will most likely be much higher than the one obtained for the same clock amplitude based on a sinusoidal clock. This solution would minimize the effect of the slope dependent ADC jitter. Nevertheless, observe that for the ADS5424, this term is small and has been optimized. Using logic gates to square a sinusoidal clock may not produce the best results as logic gates may not have been optimized to act as comparators, adding too much jitter while squaring the inputs.

The common-mode voltage of the clock inputs is set internally to 2.4 V using internal 1 kΩ resistors. It is recommended to use an ac coupling, but if for any reason, this scheme is not possible, due to, for instance, asynchronous clocking, the ADS5424 presents a good tolerance to clock common-mode variation (see Figure 20).

Additionally, the internal ADC core uses both edges of the clock for the conversion process. This means that, ideally, a 50% duty cycle should be provided. Figure 21 shows the performance variation of the ADC versus clock duty cycle.

DIGITAL OUTPUTS

The ADC provides 14 data outputs (D13 to D0, with D13 being the MSB and D0 the LSB), a data-ready signal (DRY, pin 52), and an out-of-range indicator (OVR, pin 32) that equals 1 when the output reaches the full-scale limits.

The output format is two's complement. When the input voltage is at negative full scale (around -1.1 V differential), the output will be, from MSB to LSB, 10 0000 0000 0000. Then, as the input voltage is increased, the output switches to 10 0000 0000 0001, 10 0000 0000 0010 and so on until 11 1111 1111 1111 right before mid-scale (when both inputs are tight together if we neglect offset errors). Further increases on input voltage, outputs the word 00 0000 0000 0000, to be followed by 00 0000 0000 0001, 00 0000 0000 0010 and so on until reaching 01 1111 1111 1111 at full-scale input (1.1-V differential).

Although the output circuitry of the ADS5424 has been designed to minimize the noise produced by the transients of the data switching, care must be taken when designing the circuitry reading the ADS5424 outputs. Output load capacitance should be minimized by minimizing the load on the output traces, reducing their length and the number of gates connected to them, and by the use of a series resistor with each pin. Typical numbers on the data sheet tables and graphs are obtained with 100 Ω series resistor on each digital output pin, followed by a 74AVC16244 digital buffer as the one used in the evaluation board.

POWER SUPPLIES

The use of low noise power supplies with adequate decoupling is recommended, being the linear supplies the first choice versus switched ones, which tend to generate more noise components that can be coupled to the ADS5424.

APPLICATION INFORMATION

The ADS5424 uses two power supplies. For the analog portion of the design, a 5 V AV_{DD} is used, while for the digital outputs supply (DRV_{DD}), we recommend the use of 3.3 V. All the ground pins are marked as GND, although AGND pins and DRGND pins are not tied together inside the package. Customers willing to experiment with different grounding schemes should know that AGND pins are 4, 7, 10, 13, 15, 17, 19, 21, 23, 25, 27, and 29, while DRGND pins are 2, 34, and 42. Nevertheless, we recommend that both grounds are tied together externally, using a common ground plane. That is the case on the production test boards and modules provided to customer for evaluation. In order to obtain the best performance, user should layout the board to assure that the digital return currents do not flow under the analog portion of the board. This can be achieved without the need to split the board and just with careful component placing and increasing the number of vias and ground planes.

Finally, notice that the metallic heat sink under the package is also connected to analog ground.

LAYOUT INFORMATION

The evaluation board represents a good guideline of how to layout the board to obtain the maximum performance out of the ADS5424. General design rules as the use of multilayer boards, single ground plane for both, analog and digital ADC ground connections and local decoupling ceramic chip capacitors should be applied. The input traces should be isolated from any external source of interference or noise, including the digital outputs as well as the clock traces. Clock should also be isolated from other signals, especially on applications where low jitter is required, as high IF sampling.

Besides performance oriented rules, special care has to be taken when considering the heat dissipation out of the device. The thermal heat sink (octagonal, with 2,5 mm on each side) should be soldered to the board, and provision for more than 16 ground vias should be made. The thermal package information describes the T_{JA} values obtained on the different configurations.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ADS5424IPGP	Active	Production	HTQFP (PGP) 52	160 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5424IPGP
ADS5424IPGP.B	Active	Production	HTQFP (PGP) 52	160 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5424IPGP
ADS5424IPGPG4	Active	Production	HTQFP (PGP) 52	160 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5424IPGP
ADS5424IPGPG4.B	Active	Production	HTQFP (PGP) 52	160 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5424IPGP
ADS5424IPGPR	Active	Production	HTQFP (PGP) 52	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5424IPGP
ADS5424IPGPR.B	Active	Production	HTQFP (PGP) 52	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5424IPGP

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF ADS5424 :

- Space : [ADS5424-SP](#)

NOTE: Qualified Version Definitions:

- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS5424IPGPR	HTQFP	PGP	52	1000	330.0	24.4	13.0	13.0	1.5	16.0	24.0	Q2

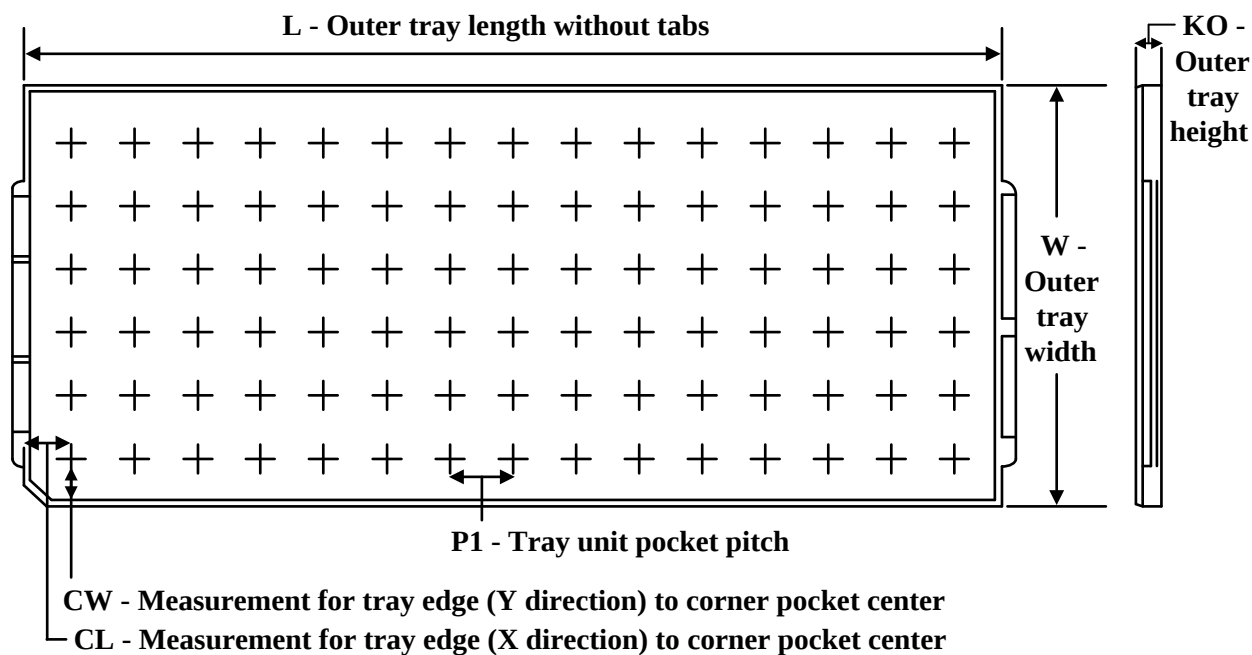
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADS5424IPGPR	HTQFP	PGP	52	1000	350.0	350.0	43.0

TRAY



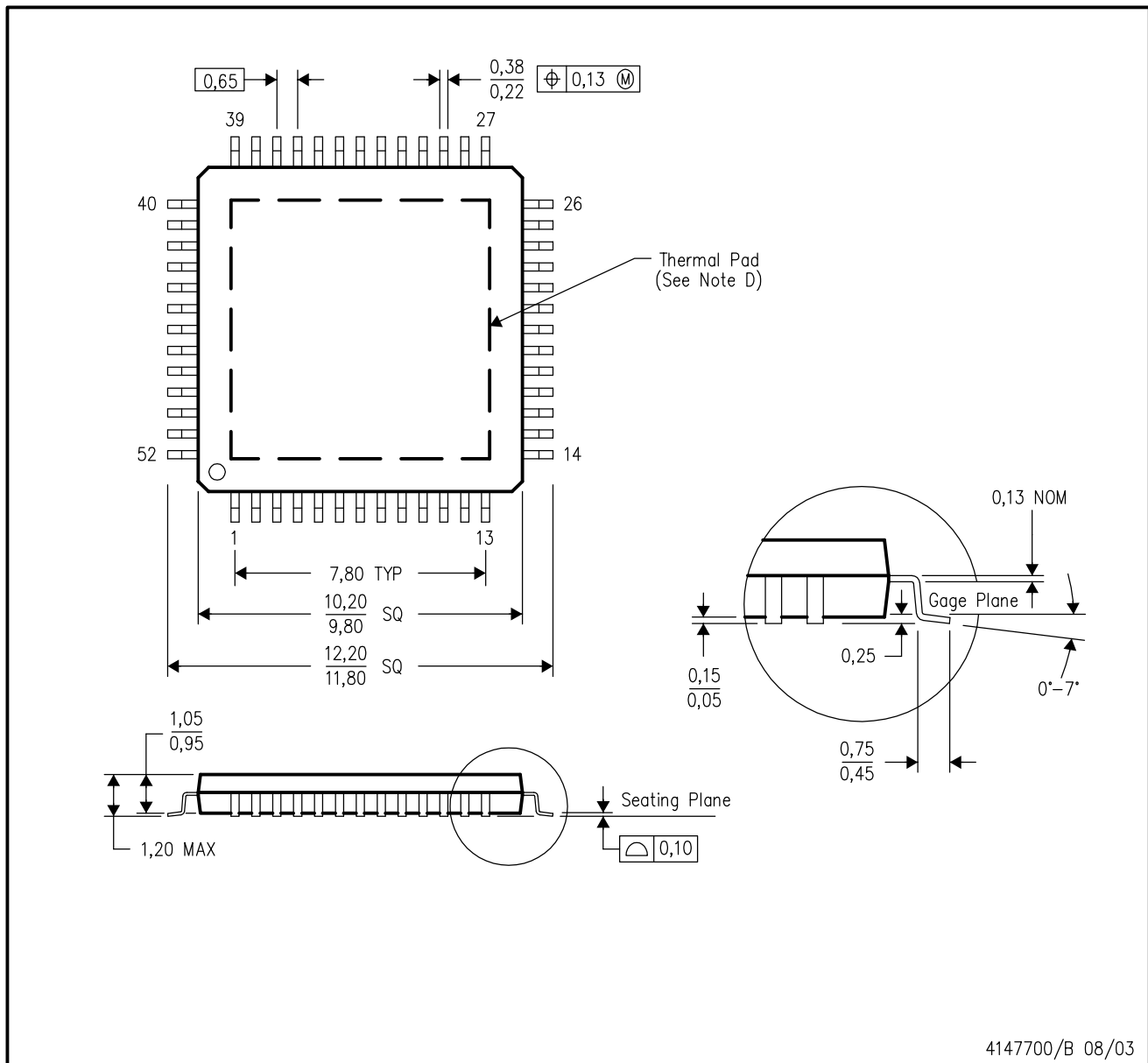
Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (μm)	P1 (mm)	CL (mm)	CW (mm)
ADS5424IPGP	PGP	HTQFP	52	160	8 x 20	150	315	135.9	7620	15.2	13.1	13
ADS5424IPGP.B	PGP	HTQFP	52	160	8 x 20	150	315	135.9	7620	15.2	13.1	13
ADS5424IPGPG4	PGP	HTQFP	52	160	8 x 20	150	315	135.9	7620	15.2	13.1	13
ADS5424IPGPG4.B	PGP	HTQFP	52	160	8 x 20	150	315	135.9	7620	15.2	13.1	13

PGP (S-PQFP-G52)

PowerPAD™ PLASTIC QUAD FLATPACK



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - E. Falls within JEDEC MS-026

PGP (S-PQFP-G52)

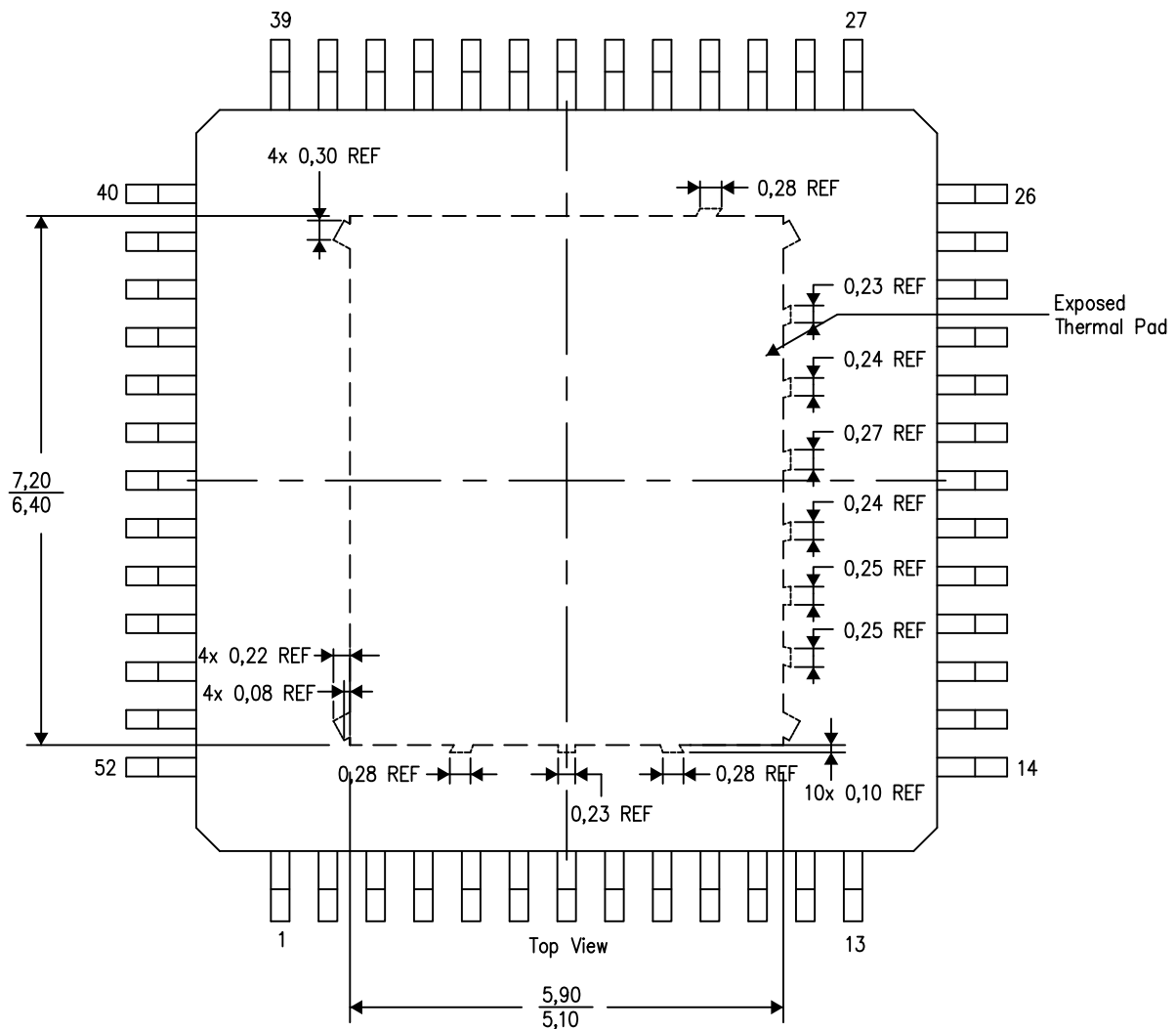
PLASTIC QUAD FLATPACK

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



4210154-4/B 11/13

NOTE: All linear dimensions are in millimeters

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